

REMARKS

This is a full and timely response to the Office Action mailed August 8, 2003.

By this Amendment, claims 1, 5, 7-11, 13 and 14 have been amended. Support for the claim amendments can be readily found throughout the specification and drawings, see for example, page 10 (lines 3-9), Figs. 1A-1C, page 14 (last two lines) and page 15 (lines 1-3). Claims 1-14 are pending in this application. By this Amendment, Applicants believe that all pending claims are in condition for allowance. Reexamination and reconsideration in light of the above amendments and the following remarks are courteously requested.

Priority Acknowledgement

The acknowledgement of the claim for foreign priority and the receipt of the certified copies supporting that claim are noted with appreciation.

Rejections under 35 U.S.C. §102

Claims 1, 2, 4, 5, 7-10 and 14 are rejected under 35 U.S.C. § 102(b) as being anticipated by Eida et al. (U.S. Patent 5,909,081). Applicant respectfully traverses this rejection.

To establish anticipation under U.S. practice, the Eida et al. reference must teach each and every limitation of the claims. Here, in this case, Eida et al. fail to teach the claim

limitations of (1) "a support substrate provided with light-emitting devices and inter-device wiring in a display region", (2) "said black matrix formed in a pattern to cover at least said inter-device wiring", and (3) "a sealing adhesive resin charged and **filling the space** between said support substrate and said opposed substrate in the condition of sealing said light-emitting devices". Further, the reference also fails to teach "alignment marks being located outside of the display region."

Eida et al. teach a support substrate provided with light-emitting devices and a transparent opposed substrate provided with a black matrix and disposed on the side of the surface forming the light-emitting device of said support substrate. Eida et al. also teach a fluorescent layer disposed to correspond to a transparent electrode or electrode of the organic EL device to absorb the light emitted from the organic EL device and to emit visible fluorescent light. However, Eida et al. clearly fail to teach a "black matrix formed in a pattern to cover at least said inter-device wiring." In Eida et al. the black matrix 9b is disposed between the fluorescent layers or color filters to prevent light leakage and thereby promote the visibility of multi-color emitted light.

In contrast, the black matrix of the present invention is formed in a pattern so as to cover at least the inter-device wirings. As stated on pages 3 and 4 of the specification, reflectance of external light at the surfaces of the inter-device

wiring is high, and the light h incident from the side of the transparent substrate is reflected by the inter-device wiring, causing a lowering in the contrast of the display unit. By forming a pattern to cover at least the inter-device wirings, external light incident from the side of the transparent opposed substrate for sealing the light-emitting devices is prevented from reaching the spaces between the light-emitting devices. In addition, reflection of the external light at the surfaces of the inter-device wirings can be prevented, and only the light emitted from the light-emitting devices is picked up from the side of the opposed substrate by being transmitted through the adhesive resin and the opposed substrate. Therefore, it is possible to enhance the contrast of the upper surface light-emitting-type display unit in which the light emitted from the light-emitting devices is picked up from the side opposite to the support substrate.

Furthermore, in Fig. 5 of Eida et al., the adhesion resin does not fill the space between the substrate 2 and the substrate 4. Conversely, in the present invention, the *sealing adhesive resin **does fill the space** between the support substrate and the opposed substrate to seal the light-emitting devices*. This is important because if air or inactive gas and not adhesive resin is between the support substrate and the opposed substrate, light will be strongly reflected at the interface of glass and gas. Thus, filling the space between the support substrate and the opposed substrate with sealing adhesive resin to seal the light-

emitting devices prevents such reflection of light. (See enclosed drawing)

In addition, Applicants have reviewed the teachings of Eida et al. and do not believe that "a laminate film having a *predetermined reflected-light-attenuation structure or resin material*" (as set forth in claim 4) is taught in the reference. Eida et al. only teach a fluorescent layer and a transparent inorganic oxide substrate in between the black matrix and electrode. Given the purpose and composition of the fluorescent layer and a transparent inorganic oxide substrate, Applicants do not believe that these elements fall within the claim limitation recited in claim 4. Also, in reviewing pages 15 and 16 of the specification, it is clear that the fluorescent layer and transparent inorganic oxide substrate taught in Eida et al. are not within the scope of claim 4.

With regard to claims 5, 10 and 14, Applicants have amended these claims to specify that the alignment marks are located outside of the display region and thus, should clearly exclude the electrodes and black matrix within the display region as being construed as alignment marks.

For claims 9 and 10, these claims have been amended to more clearly specify that the support substrate and the opposed substrate are aligned into a predetermined condition using alignment marks so that the black matrix is disposed to cover at least the inter-device wiring. In other words, the black matrix is not necessarily pattern-formed so as to cover entirely the

spaces between the light-emitting devices. Instead, it is pattern-formed to cover at least the inter-device wirings. (See pages 14 and 15 of the specification)

Thus, in view of the above amendments and arguments, withdrawal of this rejection is respectfully requested.

Rejections under 35 U.S.C. §103

Claims 3 and 6 are rejected under 35 U.S.C. 103(a) as being obvious over Eida et al. (U.S. Patent 5,909,081). Applicant respectfully traverses this rejection.

Since claims 3 and 6 are dependent claims which encompass all the limitations of claim 1, the rejection should be withdrawn for the same reasons noted above.

Claims 11-13 are rejected under 35 U.S.C. 103(a) as being obvious over Eida et al. (U.S. Patent 5,909,081) in further view of Miyamoto et al. (U.S. Patent 6,039,896). Applicant respectfully traverses this rejection.

To establish a *prima facie* case of obviousness, the cited references in combination must teach or suggest the invention as a whole, including all the limitations of the claims. Since Eida et al. fail to teach or suggest the limitations noted above which is not cured by Miyamoto et al., this rejection also cannot be sustained and should be withdrawn.

Applicants also believe that the Examiner has misunderstood and misconstrued the teachings of Miyamoto et al. The Examiner

has cited Miyamoto et al. since the reference teaches that "when a thermoplastic resin type anisotropic conductive adhesive is used, it is not difficult to repair defects after bonding because the uncured resin is easy to dissolve with a solvent" However, the Examiner has misconstrued this passage since Miyamoto et al. also further states that "it is difficult to debond fine circuits after they have been bonded with a thermoset resin type anisotropic conductive adhesive to correct defects, for example, misalignment, without breakage or damage of the bonded parts" (see column 2, lines 6-13, in its entirety). In other words, Miyamoto et al. teach that even though "it is not difficult to repair defects after bonding with an **uncured** thermoplastic resin type anisotropic conductive adhesive, it is still difficult to repair misalignment of fine circuits after bonding with an **uncured** thermoset resin type anisotropic conductive adhesive since the bonded part will break or be damaged"

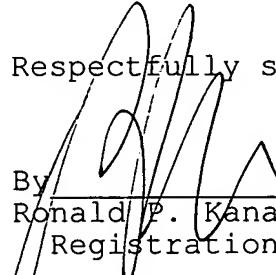
Thus, Miyamoto et al. do not teach or render obvious the inventions of claims 11-13 in which the support substrate and opposed substrate are adhered to each other through an uncured adhesive resin to allow for correction and repair of misalignment. Accordingly, withdrawal of this rejection is respectfully requested.

CONCLUSION

For the foregoing reasons, all the claims now pending in the present application are believed to be clearly patentable over the outstanding rejections. Accordingly, favorable reconsideration of the claims in light of the above remarks is courteously solicited. If the Examiner has any comments or suggestions that could place this application in even better form, the Examiner is requested to telephone Lee Cheng or the undersigned attorney at the below-listed number.

Dated: October 22, 2003

Respectfully submitted,

By 

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